| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|-----------------------|-----------------------|
| 1 | 2 | (("6613685") or ("6183565")).PN. | USPAT; | 2004/01/06 11:51 |
| | ł | | US-PGPUB | 0004/04/00 40 40 |
| 2 | 22 | ("3854443" "3947236" "4495024" "4560590" "4574093" | USPAT | 2004/01/06 12:48 |
| | | "4575408" "4622918" "4662987" "4903717" "4958061" "5318801" "5356476" "5431700" "5447431" "5520536" | | |
| | | "5542559" "5772770" "5778968" "5881208" "5927077" | | |
| [| | "5937541" "5960159").PN. | | |
| 3 | 27 | ("3854443" "3947236" "4495024" "4560590" "4574093" | USPAT | 2004/01/06 13:00 |
| | | "4575408" "4622918" "4662987" "4903717" "4903754" | | |
| | | "4958061" "5318801" "5356476" "5431700" "5447431" | | |
| | | "5520538" "5542559" "5772770" "5778968" "5881208" "5927077" "5937541" "5960159" "5997588" "6001175" | | |
| | | "6099056" "6183565").PN. | | |
| 4 | 0 | 6613685.URPN. | USPAT | 2004/01/06 13:25 |
| 5 | 4 | 6183565.URPN. | USPAT | 2004/01/06 13:26 |
| 6 | 0 | 6461439.URPN. | USPAT | 2004/01/06 13:31 |
| 7 | 25 | ("3854443" "3947236" "4495024" "4560590" "4574093" | USPAT | 2004/01/06 13:31 |
| | | "4575408" "4662918" "4662987" "4903717" "4903754" "4958061" "5318801" "5356476" "5431700" "5447431" | | |
| | | "5520538" "5542559" "5772770" "5778968" "5881208" | | |
| | | "5927077" "5937541" "5960159" "6099056" | | |
| | , | "6183565").PN. | | |
| 8 | 25 | ("3854443" "3947236" "4495024" "4560590" "4574093" | USPAT | 2004/01/06 13:34 |
| | | "4575408" "4662918" "4662987" "4903717" "4903754" | | |
| | | "4958061" "5318801" "5356476" "5431700" "5447431" "5520538" "5542559" "5772770" "5778968" "5881208" | | |
| 1 | | "5927077" "5937541" "5960159" "6099056" | | |
| | | "6183565").PN. | | |
| 9 | 1940 | ((floating or floated or float) adj (wafer or substrate or object or | USPAT; | 2004/01/06 14:23 |
| | | semiconductor or workpiece)) | US-PGPUB; | |
| 1 | | | EPO; JPO; DERWENT; | |
| | | | IBM_TDB | |
| 10 | 122 | (((floating or floated or float) adj (wafer or substrate or object | USPAT; | 2004/01/06 13:50 |
| 1 | | or semiconductor or workpiece))) and (heat or heating or | US-PGPUB; | |
| | | heated).clm. | EPO; JPO; | |
| | | | DERWENT; | |
| 11 | 0 | 20020002951.URPN. | USPAT | 2004/01/06 13:57 |
| 12 | 6 | ("4495024" "4560590" "4575408" "5314848" "6018616" | USPAT | 2004/01/06 14:04 |
| | | "6097005").PN. | | |
| 13 | 160 | ((floating or floated or float) adj (wafer or substrate or object or | USPAT; | 2004/01/06 14:23 |
| | | semiconductor or workpiece)).clm. | US-PGPUB; | |
| | | | EPO; JPO; DERWENT; | |
| | : | | IBM TDB | |
| 14 | 160 | (((floating or floated or float) adj (wafer or substrate or object | USPAT; | 2004/01/06 14:23 |
| 1 | | or semiconductor or workpiece)).clm.) not (("4495024" | US-PGPUB; | |
| | | "4560590" "4575408" "5314848" "6018616" | EPO; JPO; | |
| | | "6097005").PN.) | DERWENT; | |
| 15 | 160 | ((floating or floated or float) adj (wafer or substrate or object or | USPAT; | 2004/01/06 14:24 |
| 10 | 100 | semiconductor or workpiece)).clm. | US-PGPUB; | 200 110 1100 1 11.2 1 |
| | 1 | ,,, | EPO; JPO; | |
| | | | DERWENT; | • |
| 40 | 100 | /// | IBM_TDB | 2004/01/06 14:27 |
| 16 | 130 | (((floating or floated or float) adj (wafer or substrate or object or semiconductor or workpiece)).clm.) not (((floating or floated | USPAT; US-PGPUB; | 2004/01/06 14:27 |
| | | or float) adj (wafer or substrate or object or semiconductor or | EPO; JPO; | |
| | | workpiece))) and (heat or heating or heated).clm.) | DERWENT; | |
| | | | IBM_TDB | |
| 17 | 1688 | (((floating or floated or float) adj (wafer or substrate or object | USPAT; | 2004/01/06 14:30 |
| | | or semiconductor or workpiece))) not ((((floating or floated or | US-PGPUB; | |
| | | float) adj (wafer or substrate or object or semiconductor or workpiece)).clm.) or ((((floating or floated or float) adj (wafer or | EPO; JPO; DERWENT; | |
| 1 | | substrate or object or semiconductor or workpiece))) and (heat | IBM_TDB | |
| | | or heating or heated).clm.)) | | |

| [- | 127 | (float\$ adj wafer) | USPAT | 2004/01/06 13:35 |
|----------|-----|---|---------|------------------|
| _ | 755 | (float\$ adj (wafer or substrate or workpiece)) | USPAT; | 2001/07/31 17:45 |
| | | | JPO; | |
| | | | DERWENT | |
| _ | 6 | ((float\$ adj (wafer or substrate or workpiece))) and (pulse | USPAT; | 2001/07/31 17:46 |
| | | same energy) | JPO; | |
| <u> </u> | | 37 , | DERWENT | |
| 1 - | 93 | ((float\$ adj (wafer or substrate or workpiece))) and pulse | USPAT; | 2001/07/31 17:48 |
| | | | JPO; | |
| | | | DERWENT | |